

Data sheet acquired from Harris Semiconductor SCHS209A

# CD74HC4067, CD74HCT4067

# High-Speed CMOS Logic 16-Channel Analog Multiplexer/Demultiplexer

February 1998 - Revised July 2000

#### Features

- Wide Analog Input Voltage Range
- Low "ON" Resistance

- V <sub>CC</sub> = 4.5V	<b>70</b> Ω(Typ
- Vcc = 6V	600 (Tvn

- · Fast Switching and Propagation Speeds
- "Break-Before-Make" Switching. . . . . 6ns (Typ) at 4.5V
- Available in Both Narrow and Wide-Body Plastic Packages
- Fanout (Over Temperature Range)
- Wide Operating Temperature Range ... -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL}$  = 30%,  $N_{IH}$  = 30% of  $V_{CC}$  at  $V_{CC}$  = 5V
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,
     V<sub>IL</sub>= 0.8V (Max), V<sub>IH</sub> = 2V (Min)
  - CMOS Input Compatibility, I<sub>I</sub>  $\leq$  1 $\mu$ A at V<sub>OL</sub>, V<sub>OH</sub>

### Description

The CD74HC4067 and CD74HCT4067 devices are digitally controlled analog switches that utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL, with the low power consumption of standard CMOS integrated circuits.

These analog multiplexers/demultiplexers control analog voltages that may vary across the voltage supply range. They are bidirectional switches thus allowing any analog input to be used as an output and vice-versa. The switches have low "on" resistance and low "off" leakages. In addition, these devices have an enable control which when high will disable all switches to their "off" state.

### Ordering Information

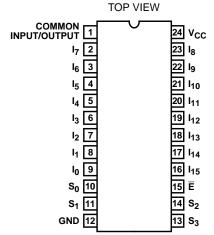
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD74HC4067E	-55 to 125	24 Ld PDIP
CD74HC4067M	-55 to 125	24 Ld SOIC
CD74HC4067SM	-55 to 125	24 Ld SSOP
CD74HCT4067M	-55 to 125	24 Ld SOIC

#### NOTES:

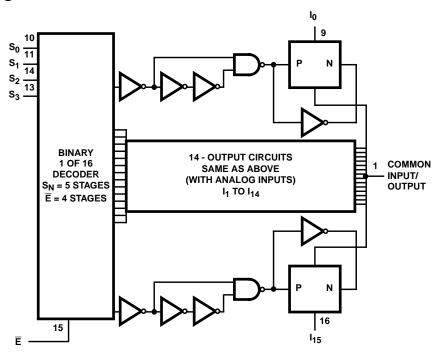
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer and die is available that meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.

#### **Pinout**

## CD74HC4067, CD74HCT4067 (PDIP, SOIC, SSOP)



# Functional Diagram



#### **TRUTH TABLE**

S0	<b>S</b> 1	<b>S</b> 2	<b>S</b> 3	Ē	SELECTED CHANNEL
Х	Х	Х	Х	1	None
0	0	0	0	0	0
1	0	0	0	0	1
0	1	0	0	0	2
1	1	0	0	0	3
0	0	1	0	0	4
1	0	1	0	0	5
0	1	1	0	0	6
1	1	1	0	0	7
0	0	0	1	0	8
1	0	0	1	0	9
0	1	0	1	0	10
1	1	0	1	0	11
0	0	1	1	0	12
1	0	1	1	0	13
0	1	1	1	0	14
1	1	1	1	0	15

### NOTE:

H = High Level

L = Low Level

X = Don't Care

## **Absolute Maximum Ratings**

OC Supply Voltage, V <sub>CC</sub>
(Voltages Referenced to Ground)0.5V to 7V
OC Input Diode Current, I <sub>IK</sub>
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$
OC Drain Current, IO
For $-0.5V < V_O < V_{CC} + 0.5V$
OC Output Diode Current, IOK
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$
OC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$
OC V <sub>CC</sub> or Ground Current, I <sub>CC</sub>

#### **Thermal Information**

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ (oC/W)
E Package	67
M Package	46
SM Package	63
Maximum Junction Temperature (Plastic Package)	150°C
Maximum Storage Temperature Range6	65°C to 150°C

### **Operating Conditions**

Temperature Range, T <sub>A</sub>	55 <sup>0</sup> C to 125 <sup>0</sup> C
HC Types	
HCT Types	
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub>	0V to V <sub>CC</sub>
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE

3.  $\theta_{JA}$  is calculated in accordance with JESD 51.

### **DC Electrical Specifications**

		TE CONDI				25°C	25°C -40°C TO 85°C		-55°C T	O 125°C			
PARAMETER	SYMBOL	V <sub>I</sub> (V)	V <sub>IS</sub> (V)	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS	
HC TYPES													
High Level Input	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V	
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	٧	
				6	4.2	-	-	4.2	-	4.2	-	٧	
Low Level Input	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	٧	
Voltage					4.5	-	-	1.35	-	1.35	-	1.35	٧
				6	-	-	1.8	-	1.8	-	1.8	V	
Maximum "ON"	R <sub>ON</sub>	V <sub>CC</sub> or	V <sub>CC</sub> or	4.5	-	70	160	-	200	-	240	Ω	
Resistance I <sub>O</sub> = 1mA		GND G	GND	6	-	60	140	-	175	-	210	Ω	
		V <sub>CC</sub> to	V <sub>CC</sub> to	4.5	-	90	180	-	225	-	270	Ω	
		GND	GND	6	-	80	160	-	200	-	240	Ω	
Maximum "ON"	ΔR <sub>ON</sub>	-	-	4.5	-	10	-	-	-	-	-	Ω	
Resistance Between Any Two Switches				6	-	8.5	-	-	-	-	-	Ω	
Switch "Off" Leakage Current 16 Channels	I <sub>IZ</sub>	E = V <sub>CC</sub>	V <sub>CC</sub> or GND	6	-	-	±0.8	-	±8	-	±8	μА	
Logic Input Leakage Current	lı	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	μА	
Quiescent Device Current I <sub>O</sub> = 0mA	Icc	V <sub>CC</sub> or GND	-	6	-	-	8	-	80	-	160	μА	

# DC Electrical Specifications (Continued)

		TE CONDI	ST ITIONS			25°C		-40°C TO 85°C		-55°C T	O 125°C	
PARAMETER	SYMBOL	V <sub>I</sub> (V)	V <sub>IS</sub> (V)	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HCT TYPES	HCT TYPES											
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5	-	-	0.8	-	0.8	-	0.8	V
Maximum "ON" Resistance	R <sub>ON</sub>	V <sub>CC</sub> or GND	V <sub>CC</sub> or GND	4.5	-	70	160	-	200	-	240	Ω
I <sub>O</sub> = 1mA		V <sub>CC</sub> to GND	V <sub>CC</sub> to GND	4.5	-	90	180	-	225	-	270	Ω
Maximum "ON" Resistance Between Any Two Switches	ΔR <sub>ON</sub>	-	-	4.5	-	10	-	-	-	-	-	Ω
Switch "Off" Leakage Current 16 Channels	I <sub>IZ</sub>	E = V <sub>CC</sub>	V <sub>CC</sub> or GND	6	-	-	±0.8	-	±8	-	±8	μА
Logic Input Leakage Current	II	V <sub>CC</sub> or GND (Note 5)	-	6	-	-	±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V <sub>CC</sub> or GND	-	6	-	-	8	-	80	-	160	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 4)	V <sub>CC</sub> -2.1	-	-	-	100	360	-	450	-	490	μА

#### NOTES:

- 4. For dual-supply systems theoretical worst case ( $V_I$  = 2.4V,  $V_{CC}$  = 5.5V) specification is 1.8mA.
- 5. Any voltage between  $V_{\mbox{\footnotesize CC}}$  and GND.

### **HCT Input Loading Table**

INPUT	UNIT LOAD
S <sub>0</sub> - S <sub>3</sub>	0.5
Ē	0.3

NOTE: Unit Load is  $\Delta I_{CC}$  limit specified in DC Electrical Specifications table, e.g.,  $360\mu A$  max at  $25^{\circ}C$ .

# Switching Specifications Input $t_{\text{r}}, \, t_{\text{f}} = 6 \text{ns}$

		TEST	TEST V <sub>CC</sub>		25°C		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES											
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
Switch In to Out			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
		C <sub>L</sub> = 15pF	5	-	6	-	-	-	-	-	ns
Switch Turn On	t <sub>PZH</sub> , t <sub>PZL</sub>	C <sub>L</sub> = 50pF	2	-	-	275	-	345	-	415	ns
E to Out			4.5	-	-	55	-	69	-	83	ns
			6	-	-	47	-	59	-	71	ns
		C <sub>L</sub> = 15pF	5	-	23	-	-	-	-	-	ns

# Switching Specifications Input $t_r$ , $t_f = 6ns$ (Continued)

		TEST	v <sub>cc</sub>		25°C		-40°C 1	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	CONDITIONS	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Switch Turn On	t <sub>PZH</sub> , t <sub>PZL</sub>	C <sub>L</sub> = 50pF	2	-	-	300	-	375	-	450	ns
Sn to Out			4.5	-	-	60	-	75	-	90	ns
			6	-	-	51	-	64	-	76	ns
		C <sub>L</sub> = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn Off	t <sub>PHZ</sub> , t <sub>PLZ</sub>	C <sub>L</sub> = 50pF	2	-	-	275	-	345	-	415	ns
E to Out			4.5	-	-	55	-	69	-	83	ns
			6	-	-	47	-	59	-	71	ns
		C <sub>L</sub> = 15pF	5	-	23	-	-	-	-	-	ns
Switch Turn Off	t <sub>PHZ</sub> , t <sub>PLZ</sub>	C <sub>L</sub> = 50pF	2	-	-	290	-	365	-	435	ns
Sn to Out			4.5	-	-	58	-	73	-	87	ns
			6	-	-	49	-	62	-	74	ns
		C <sub>L</sub> = 50pF	5	-	21	-	-	-	-	-	ns
Input (Control) Capacitance	C <sub>I</sub>	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 6, 7)	C <sub>PD</sub>	-	5	-	93	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay Time	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22	ns
Switch In to Out		C <sub>L</sub> = 15pF	5	-	6	-	-	-	-	-	ns
Switch Turn On	t <sub>PZH</sub> , t <sub>PZL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	60	-	75	-	90	ns
E to Out		C <sub>L</sub> = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn On	t <sub>PZH</sub> , t <sub>PZL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	60	-	75	-	90	ns
Sn to Out		C <sub>L</sub> = 15pF	5	-	25	-	-	-	-	-	ns
Switch Turn Off	t <sub>PHZ</sub> , t <sub>PLZ</sub>	C <sub>L</sub> = 50pF	4.5	-	-	55	-	69	-	83	ns
E to Out		C <sub>L</sub> = 15pF	5	-	23	-	-	-	-	-	ns
Switch Turn Off	t <sub>PHZ</sub> , t <sub>PLZ</sub>	C <sub>L</sub> = 50pF	4.5	-	-	58	-	73	-	87	ns
Sn to Out		C <sub>L</sub> = 15pF	5	-	21	-	-	-	-	-	ns
Input (Control) Capacitance	C <sub>I</sub>	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 6, 7)	C <sub>PD</sub>	-	5	-	96	-	-	-	-	-	pF

### NOTES:

<sup>6.</sup>  $C_{\mbox{\scriptsize PD}}$  is used to determine the dynamic power consumption, per package.

<sup>7.</sup>  $P_D = C_{PD} \, V_{CC}^2 \, f_i + \Sigma \, (C_L + C_S) \, V_{CC}^2 \, f_o$  where  $f_i$  = input frequency,  $f_o$  = output frequency,  $C_L$  = output load capacitance,  $C_S$  = switch capacitance,  $V_{CC}$  = supply voltage.

### Analog Channel Specifications $T_A = 25^{\circ}C$

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> (V)	НС/НСТ	UNITS
Switch Frequency Response Bandwidth at -3dB (Figure 2)	Figure 4, Notes 8, 9	4.5	89	MHz
Sine Wave Distortion	Figure 5	4.5	0.051	%
Feedthrough Noise E to Switch	Figure 6, Notes 9, 10	4.5	TBE	mV
Feedthrough Noise S to Switch			TBE	mV
Switch "OFF" Signal Feedthrough (Figure 3)	Figure 7	4.5	-75	dB
Switch Input Capacitance, C <sub>S</sub>		-	5	pF
Common Capacitance, C <sub>COM</sub>		-	50	pF

#### NOTES:

- 8. Adjust input level for 0dBm at output, f = 1MHz.
- 9.  $V_{IS}$  is centered at  $V_{CC}/2$ .
- 10. Adjust input for 0dBm at  $V_{\mbox{\scriptsize IS}}$ .

# **Typical Performance Curves**

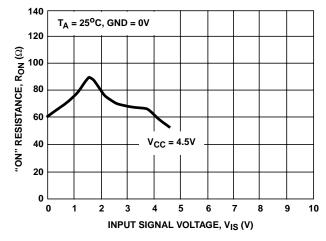


FIGURE 1. TYPICAL "ON" RESISTANCE vs INPUT SIGNAL VOLTAGE

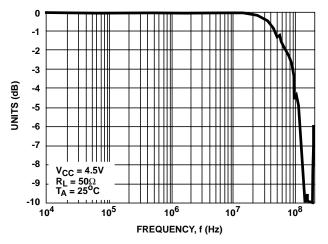


FIGURE 2. TYPICAL SWITCH FREQUENCY RESPONSE

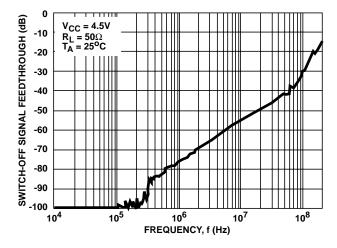


FIGURE 3. TYPICAL SWITCH-OFF SIGNAL FEEDTHROUGH vs FREQUENCY

# Analog Test Circuits

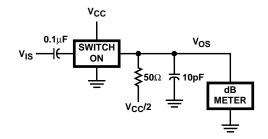


FIGURE 4. FREQUENCY RESPONSE TEST CIRCUIT

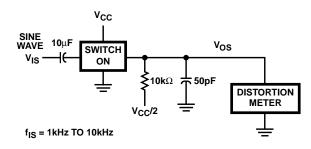


FIGURE 5. SINE WAVE DISTORTION TEST CIRCUIT

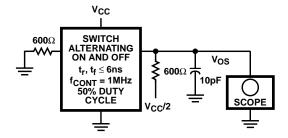


FIGURE 6. CONTROL-TO-SWITCH FEEDTHROUGH NOISE TEST CIRCUIT

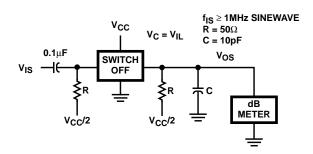


FIGURE 7. SWITCH OFF SIGNAL FEEDTHROUGH TEST CIRCUIT

### Test Circuits and Waveforms

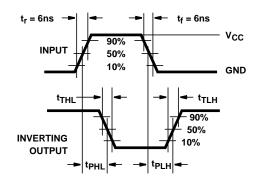


FIGURE 8. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

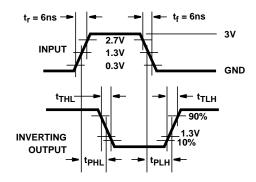


FIGURE 9. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

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